

BOARD NAME:
RS-485 HALF DUPLEX ESD SURGE

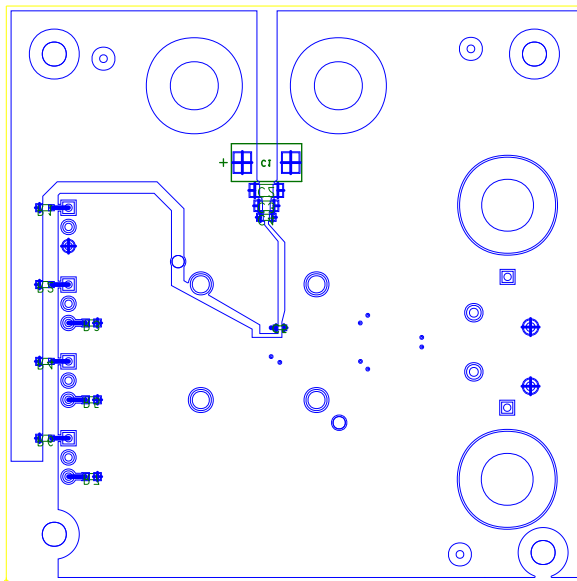
ALL ARTWORK LAYERS VIEWED FROM TOP

BOARD REV:
A

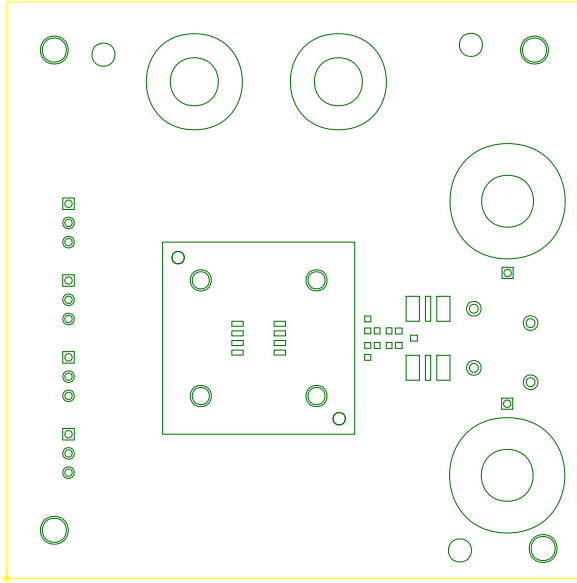
KSID:
16093

JOB NUMBER:
126503

LAYER DESCRIPTION:
~~LAYER1XXX~~TOPXSIDE



	BOARD NAME:	BOARD REV:	KSID:	JOB NUMBER:
	RS-485 HALF DUPLEX ESD SURGE	A	16093	126503
ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION:		
		LAYER 4 (XX) BOTTOM SIDE		



BOARD NAME:
RS-485 HALF DUPLEX ESD SURGE

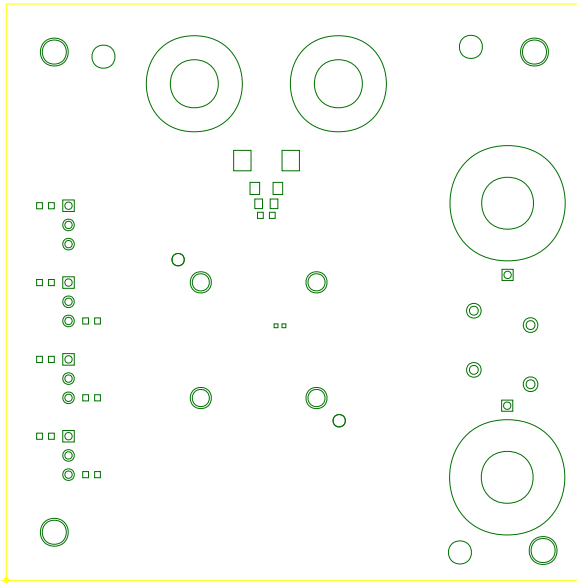
ALL ARTWORK LAYERS VIEWED FROM TOP

BOARD REV:
A

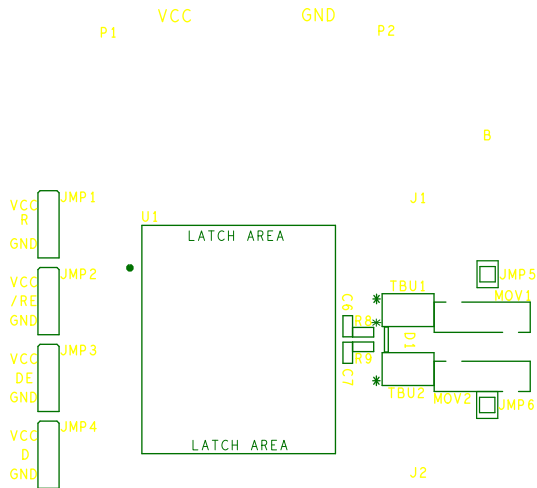
KSID:
16093

JOB NUMBER:
126503

LAYER DESCRIPTION:
XSOLDERMASKX TOPX XXXX



	BOARD NAME: RS-485 HALF DUPLEX ESD SURGE	BOARD REV: A	KSID: 16093	JOB NUMBER: 126503
	ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: SOLDER MASK	



	BOARD NAME: RS-485 HALF DUPLEX ESD SURGE	BOARD REV: A	KSID: 16093	JOB NUMBER: 126503
	ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: XSXUXSXCXDEKX XTOPX XXXX	



R1

R2

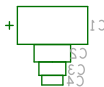
R3

R4

R5

R6

R7

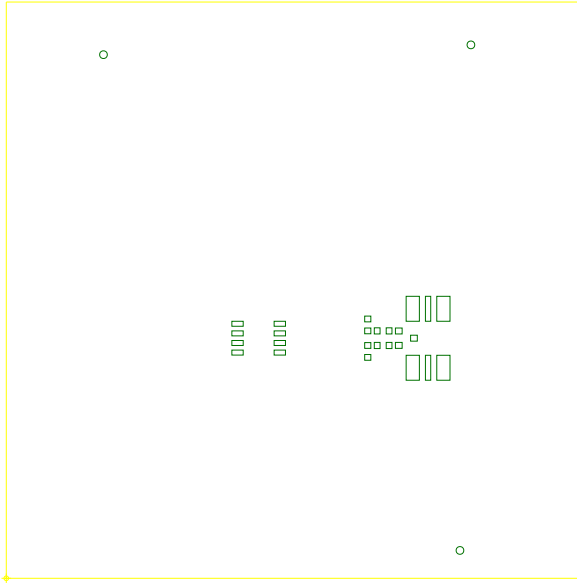


2\N:

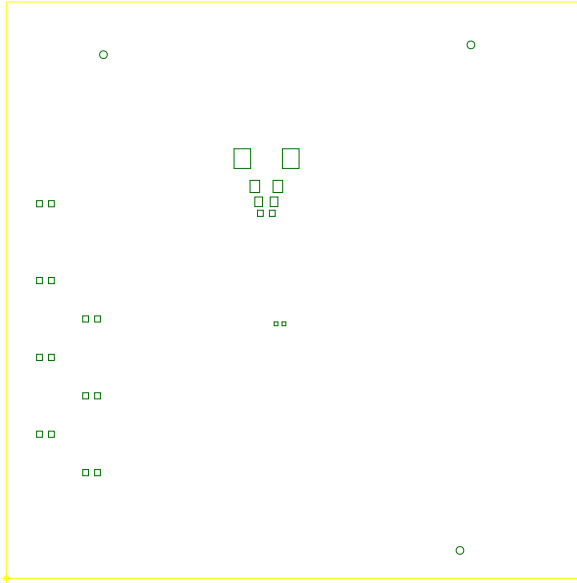
Krypton



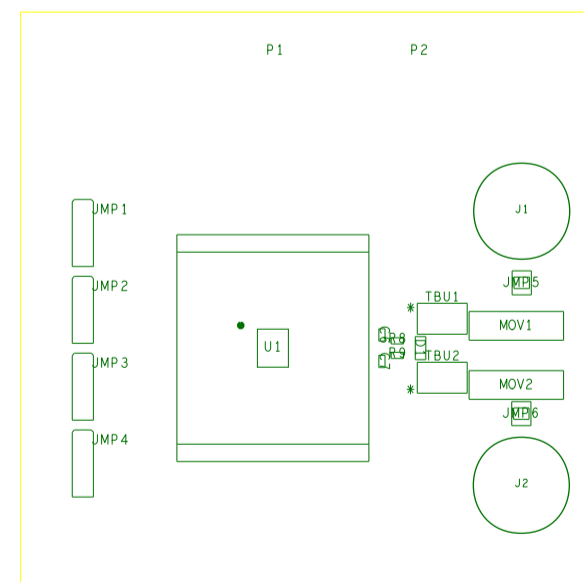
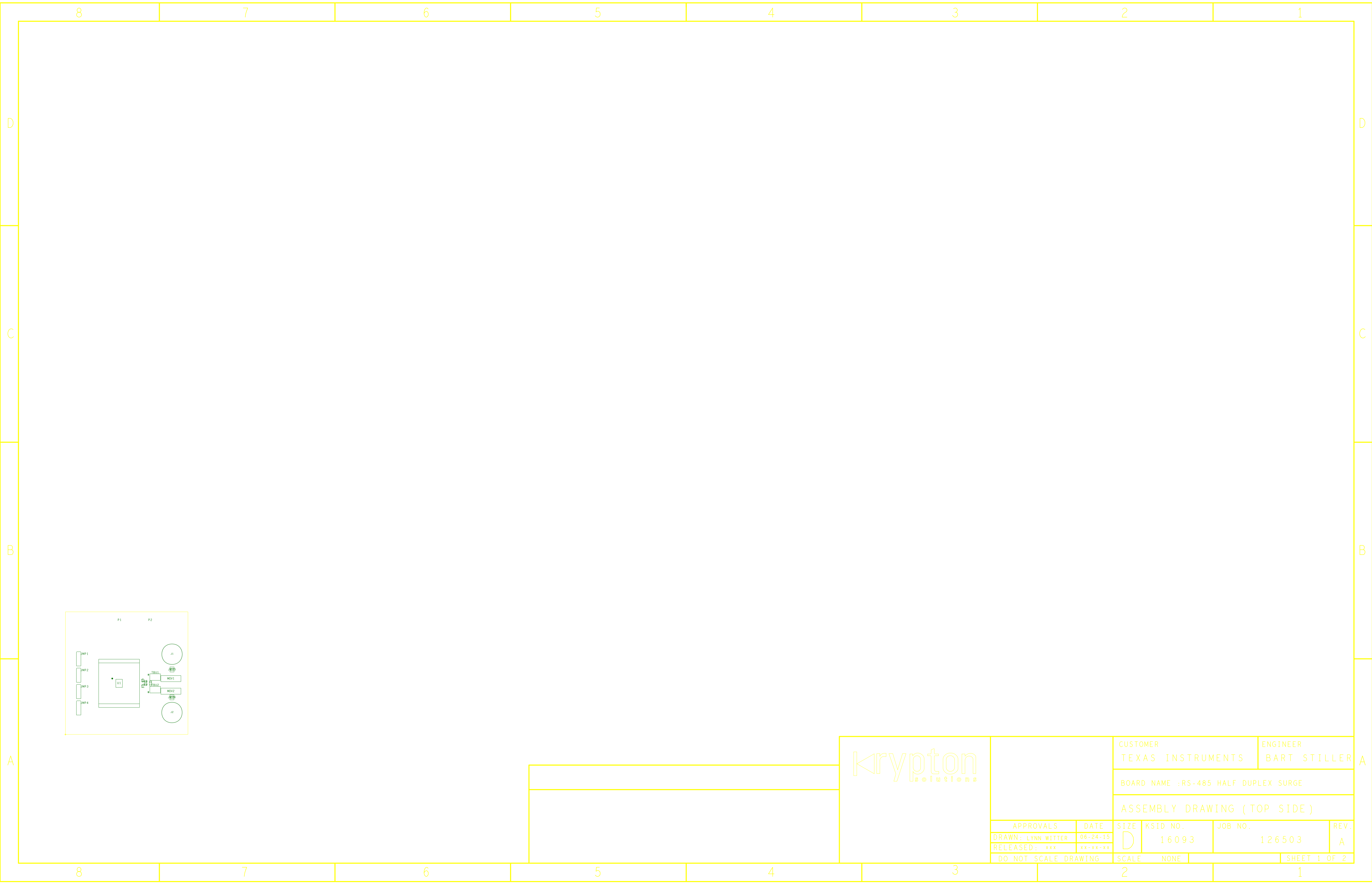
	BOARD NAME: RS-485 HALF DUPLEX ESD SURGE	BOARD REV: A	KSID: 16093	JOB NUMBER: 126503
	ALL ARTWORK LAYERS VIEWED FROM TOP		LAYER DESCRIPTION: X5XUKXSICRDEKX BXNDXOMX X	



	BOARD NAME: RS-485 HALF DUPLEX ESD SURGE	BOARD REV: A	KSID: 16093	JOB NUMBER: 126503
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: PASTEMASK/ TOPXXXXXX		



	BOARD NAME: RS-485 HALF DUPLEX ESD SURGE	BOARD REV: A	KSID: 16093	JOB NUMBER: 126503
	ALL ARTWORK LAYERS VIEWED FROM TOP	LAYER DESCRIPTION: PASTEMASK BOTTOM XX		



	CUSTOMER		TEXAS INSTRUMENTS		ENGINEER		BART STILLER	
	BOARD NAME :RS-485 HALF DUPLEX SURGE							
	ASSEMBLY DRAWING (TOP SIDE)							
	APPROVALS	DATE	SIZE	KSID NO.	JOB NO.	REV.		
DRAWN: LYNN WITTER	06-24-15	D	16093	126503	A			
RELEASED: xxx	xx-xx-xx							
DO NOT SCALE DRAWING		SCALE	NONE				SHEET 1 OF 2	

8 7 6 5 4 3 2 1

D D

C C

B B

A A

8 7 6 5 4 3 2 1

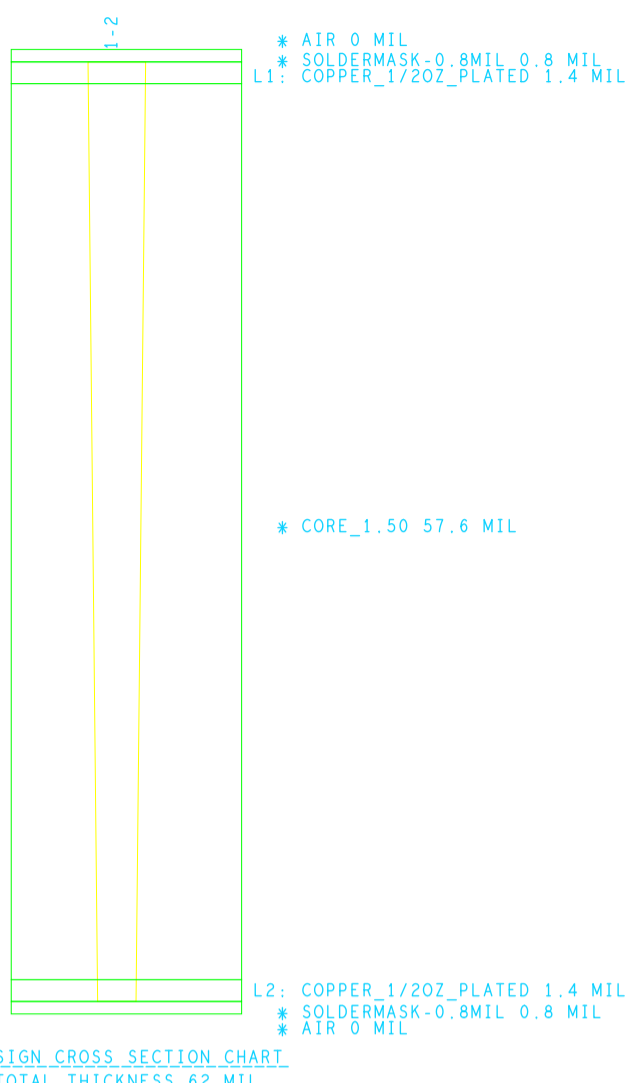


TABLE 1:

LAYER NO.	LAYER NAME	DIFFERENTIAL PAIR IMPEDANCE (OHMS)	DIFF TRACE WIDTH	DIFF TRACE SPACING	SINGLE ENDED IMPEDANCE (OHMS)	SINGLE ENDED TRACE WIDTH	REFERENCE LAYER
LAYER 1	TOP						LAYER 2
LAYER 2	L2_GND						
LAYER 3	L3_PWR						
LAYER 4	BOTTOM						LAYER 3

SPECIAL FAB NOTES:

- 1: FAB SHOP MUST FOLLOW THE SOLDER MASK REVIEW LAYERS.
- 2:

PLACE DRILL CHART HERE:

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	10.0	+3.0/-10.0	PLATED	9
.	38.0	+3.0/-3.0	PLATED	12
□	38.0	+3.0/-3.0	PLATED	2
○	46.0	+3.0/-3.0	PLATED	4
○	89.0	+3.0/-3.0	PLATED	4
⬡	250.0	+3.0/-3.0	PLATED	2
○	270.0	+2.0/-2.0	PLATED	2
R	64.0	+2.0/-2.0	NON-PLATED	2
G	125.0	+2.0/-2.0	NON-PLATED	4

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
 NUMBER OF LAYERS: 2
 MIN. TRACK WIDTH: 25.0 MIL
 MIN. CLEARANCE: X.X MIL
 MIN. VIA PAD/DRILL: 20/10 MIL

MIN. ANNULAR RING 2 MIL EXTERNAL PER IPC-6012C CLASS 2
 REGISTRATION TOLERANCES: METAL +/- X MIL, HOLES +/- X MIL
 IMPEDANCE CONTROL: NONE YES - SEE TABLE 1
 MIXED DIELECTRIC: NO YES
 LAMINATE MATERIAL:
 FR-4 HIGH Tg ROGERS 4350B OTHER: _____
 THICKNESS:
 0.062" +/-10% 0.093" +/-10% OTHER: _____
 TOLERANCE: IPC-6012C TYPE 3 CLASS 2 OTHER +/-
 BOW & TWIST:
 IPC-6012C TYPE 3 CLASS 2 OTHER +/-

COPPER THICKNESS (FINISHED):
 OUTER: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.
 INNER SIGNAL: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.
 INNER PLANE: 1/4 OZ. 1/2 OZ. 1.0 OZ. 2.0 OZ.
 OTHER: _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____

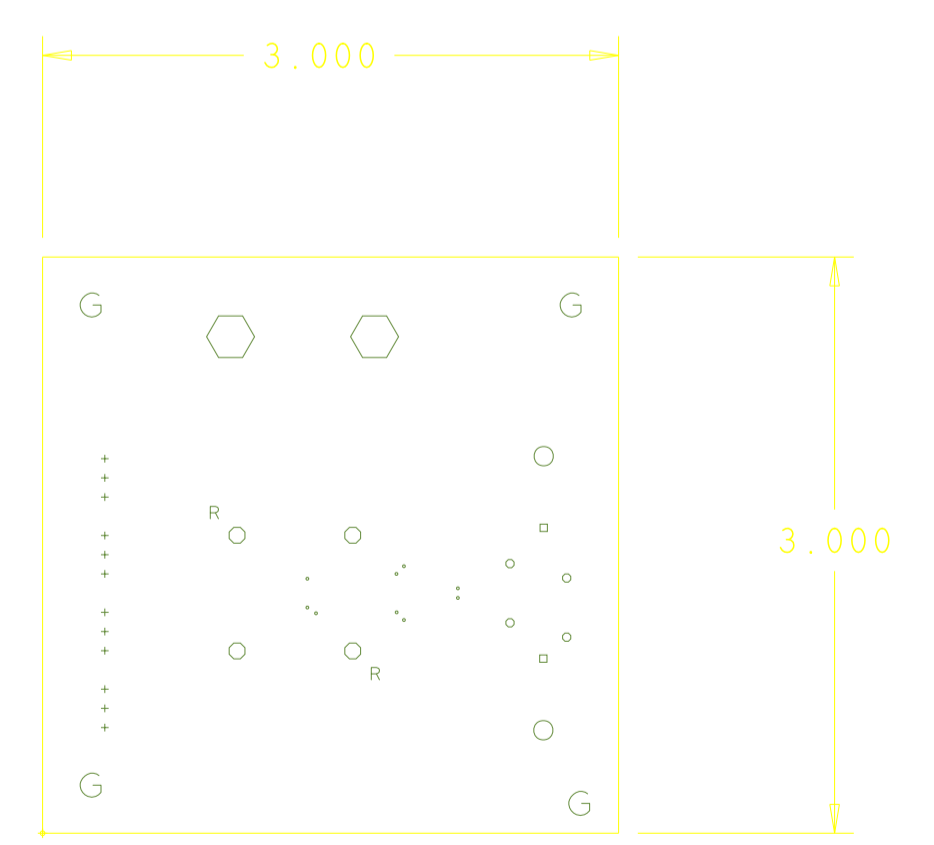
SOLDERMASK: (PER IPC-6011,6012)
 TOP BOTTOM
 SOLDERMASK COLOR: GREEN BLUE OTHER _____

THROUGH-HOLE VIA TREATMENT:
 OPEN TENTED IDENTIFIER: ALL X MIL VIAS
 VIA-FILL USING NON-CONDUCTIVE EPOXY:
 NO YES IDENTIFIER: ALL X MIL VIAS

THIEVING ALLOWED: YES NO
 BOARD SURFACE TREATMENT:
 NICKEL/GOLD (ENIG) ORGANIC (OSP) HASL ENEPIG
 IMMERSION TIN OTHER _____

FOR WIRE BONDING:
 HARD GOLD SOFT GOLD PER SUPPLIED ARTWORK
 ADDITIONAL REQUIREMENTS:
 MICRO-SECTION TDR REPORTS/COUPONS ELECTRICAL TEST
 CERTIFICATES OF COMPLIANCE RoHS UL 94V-0

VENDOR MARKING:
 VENDOR DATE CODE,UL,LOGO: ETCH SILKSCREEN BREAK-AWAY
 IN AN OPEN AREA WHERE INDICATED (SEE DRAWING)



CAD ORIGIN

	BOARD NAME: RS-485 HALF DUPLEX ESD SURGE	BOARD REV: A	KSID: 16093	JOB NUMBER: 126503
	LAYER DESCRIPTION: # MICROSECTION DRAWING			

	CUSTOMER TEXAS INSTRUMENTS	ENGINEER BART STILLER
	BOARD NAME :RS-485 HALF DUPLEX SURGE	
FABRICATION DRAWING		
APPROVALS	DATE	SIZE
DRAWN: LYNN WITTER	06-24-15	D
RELEASED: xxx	xx-xx-xx	
DO NOT SCALE DRAWING	SCALE NONE	SHEET 1 OF 1

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